Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1070-ND

ATS PART # ATS-51290K-C2-R0

Features & Benefits

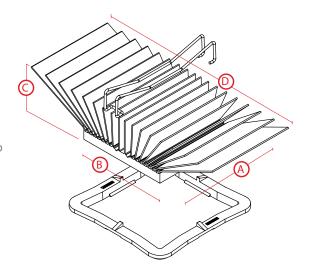
maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for low profile components from 1.5 to 2.99mm





Thermal Performance Table

| AIR VELOCITY | | THERMAL RESISTANCE | | |
|--------------|-----|--------------------|---------------|--|
| FT/MIN | M/S | °C/W (UNDUCTED) | °C/W (DUCTED) | |
| 200 | 1.0 | 4.5 | 3.4 | |
| 300 | 1.5 | 3.6 | | |
| 400 | 2.0 | 3.1 | | |
| 500 | 2.5 | 2.8 | | |
| 600 | 3.0 | 2.6 | | |
| 700 | 3.5 | 2.4 | | |
| 800 | 4.0 | 2.2 | | |

Product Details†

| DIMENSION A | DIMENSION B | DIMENSION C [§] | DIMENSION D | TIM [‡] | FINISH |
|-------------|-------------|--------------------------|-------------|------------------|-----------------|
| 29 | 29 | 14.5 | 51.74 | C1100F | BLACK- ANODIZED |

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

- * RoHS Compliant
- ‡ TIM = Thermal Interface Material
- † Dimensions are measured in millimeters
- ◆ Dimensions A & B refer to component size
- § Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



